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ELECTRONIC COMPONENT, AND
OSCILLATOR**(52) **U.S. Cl.**CPC *H03B 5/32* (2013.01); *H01L 25/165*
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24/13 (2013.01)(71) Applicant: **Seiko Epson Corporation, Tokyo (JP)**(72) Inventor: **Shinya AOKI, Minowa (JP)**(21) Appl. No.: **17/752,895**(22) Filed: **May 25, 2022**(30) **Foreign Application Priority Data**

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ABSTRACT

An electronic component package includes a lid, a first layer, a second layer disposed between the first layer and the lid and configuring a first frame, a third layer disposed between the second layer and the lid and configuring a second frame, a bonding member bonding the third layer to the lid, and a via wire electrically coupled to the lid and penetrating the second frame, in which, when an inner diameter of a first corner portion of the first frame is denoted by R1 and an inner diameter of a second corner portion of the second frame overlapping the first corner portion in a plan view is denoted by R2, $R1 < R2$, and an inner surface of the second corner portion protrudes more than an inner surface of the first corner portion in a cross-sectional view.

